

# Laser Processing of Materials

## Applications: Bending and Welding

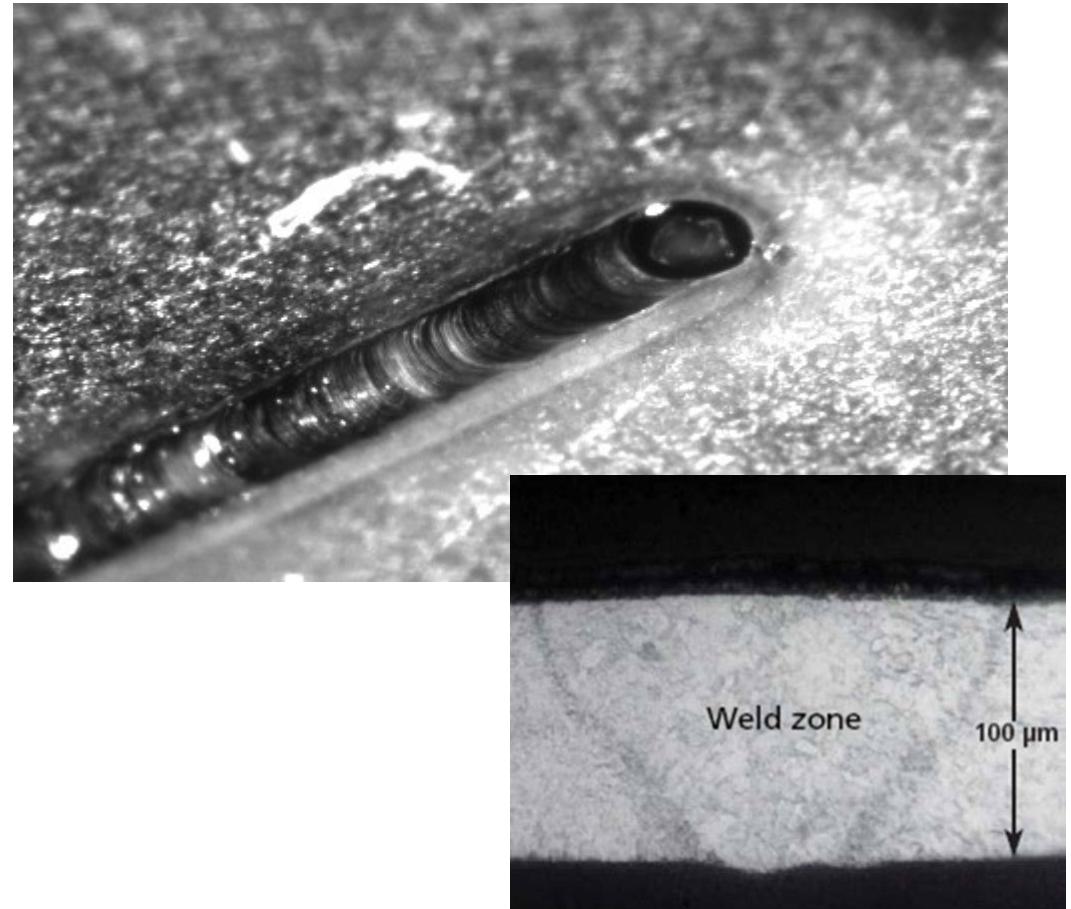
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Patrik Hoffmann

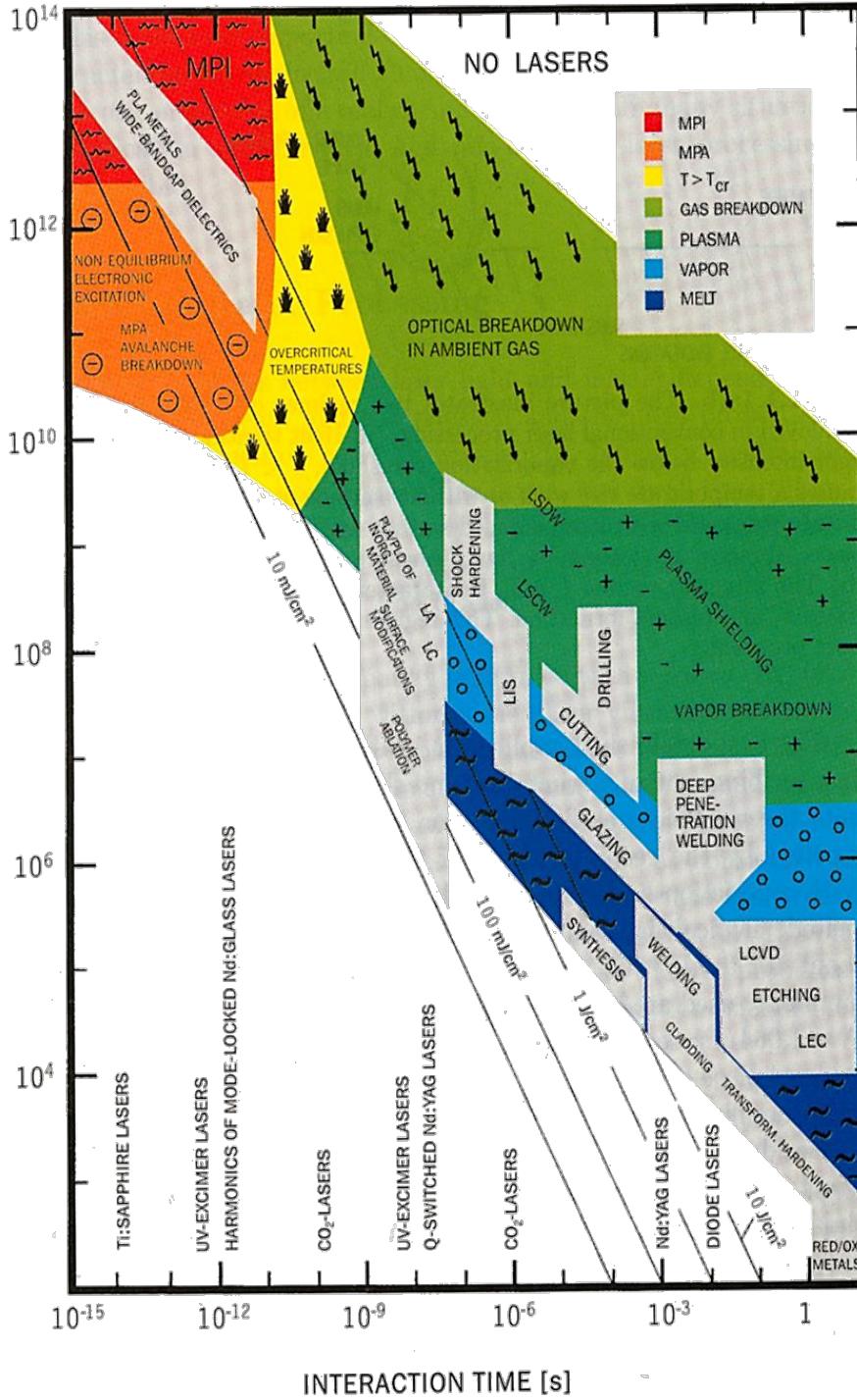
# Bending and Welding



**bending**



LASER LIGHT INTENSITY  $I$  [W/cm<sup>2</sup>]



D. Bäuerle;  
Laser Processing and Chemistry, 3rd ed.  
Springer, Berlin, 2000

What kind of laser do you propose for bending / welding?

# Application of lasers in materials processing: Intensity-Time Diagram

PLA/PLD – pulsed laser ablation/  
deposition

LA – laser annealing

LC – laser cleaning

LIS – laser induced isotope separation/IR –  
laser photochemistry

MPA/MPI – multiphoton absorption  
ionization

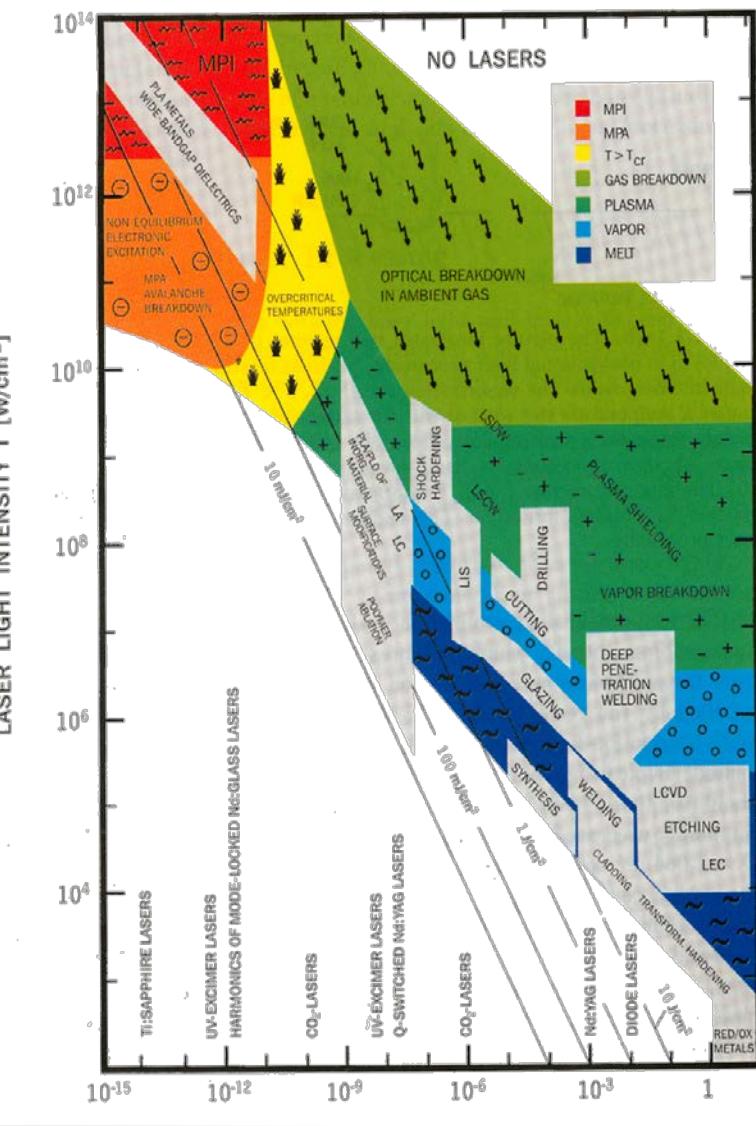
LSDW/LSCW – laser supported  
detonation/combustion waves

LCVD – laser induced chemical vapour  
deposition

LEC – laser induced electrochemical  
plating/etching

RED/OX – long pulse or cw  $\text{CO}_2$ -laser  
induced reduction/oxidation

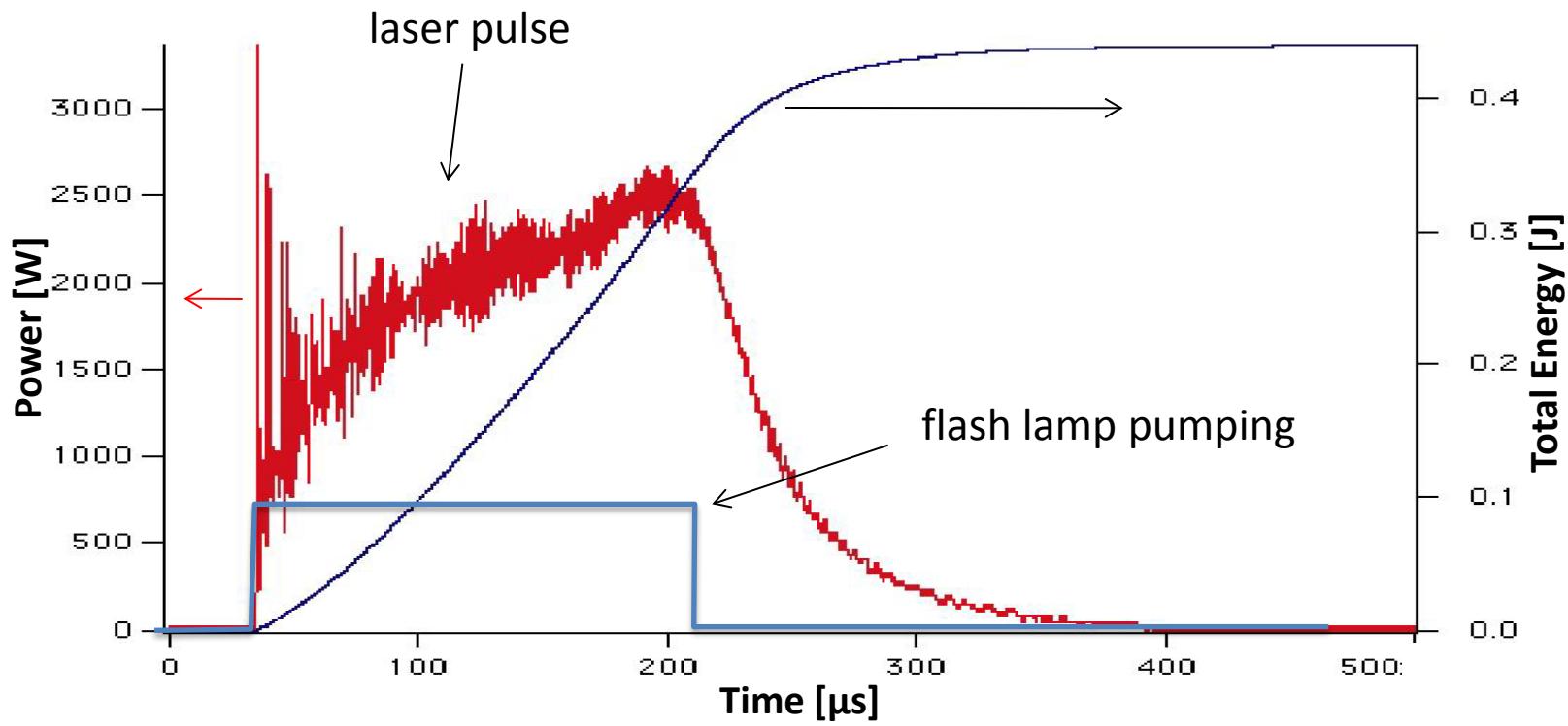
D. Bäuerle; Laser Processing and  
Chemistry, 3rd ed. Springer, Berlin,  
2000



# Laser Types: Pulsed & CW

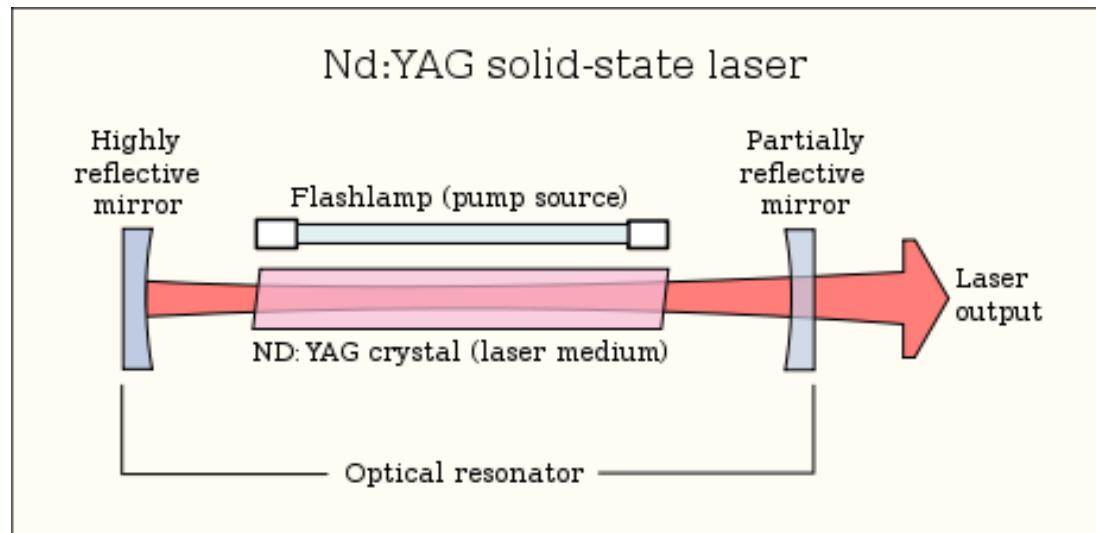
Type of laser	Pulse length determined by	Typical pulse length	Characteristic pulse peak power
Continuous wave (cw)	-	$\infty$	Ws – kWs
Free running laser	Pump pulse length (flash lamp)	100 $\mu$ s – 1ms	kWs
Q-switched laser	Time constants of active material and modulating element	1 ns – 100 ns	MWs
Mode-locked laser	Number of coupled modes, pulse compression	10 fs – 10 ps	GWs

# Free-running Lasers

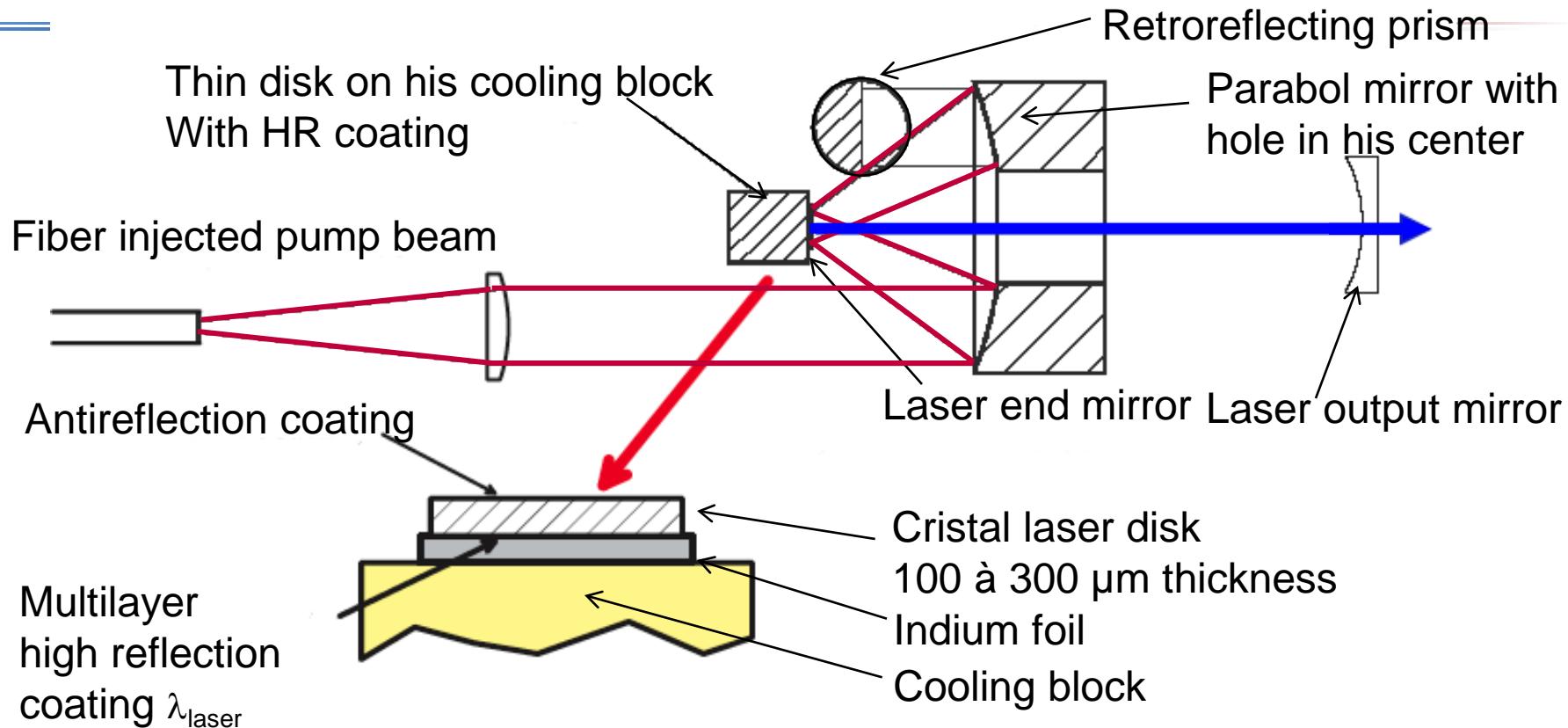


- „Free-running“ = no special pulse duration regulation
- pulse duration determined by pump duration, typically  $10 \mu\text{s} – 1 \text{ ms}$
- **peak power** is relatively **low**
- **total pulse energy** can be quite **high**

# Nd:YAG Laser- Flash Lamp Pumped



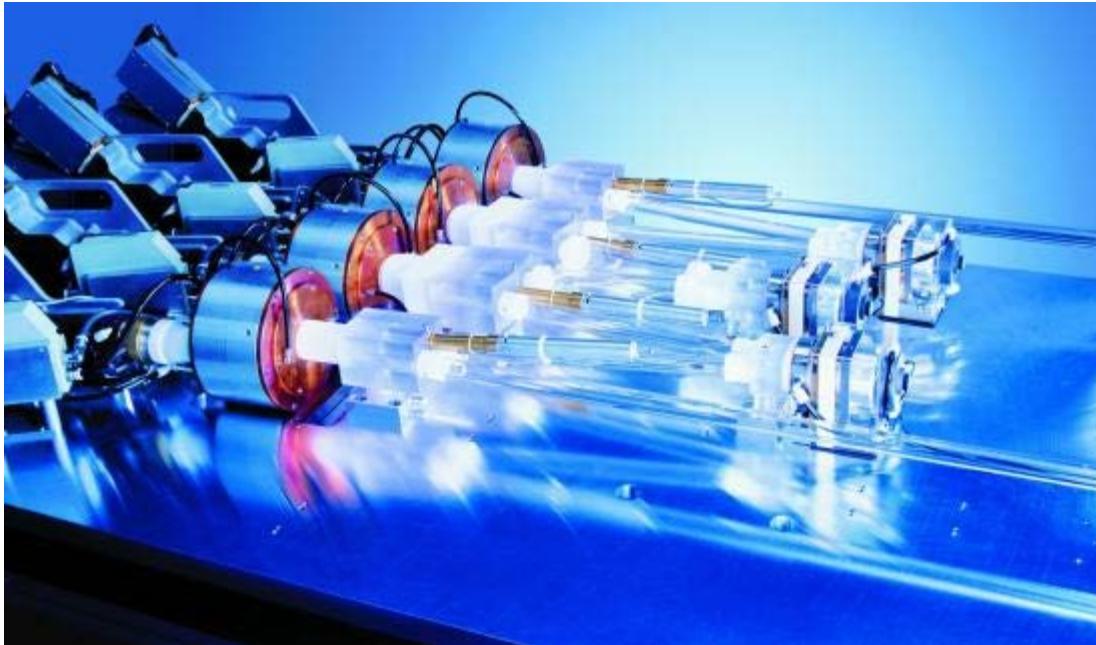
# Yb:YAG Thin Disc Laser



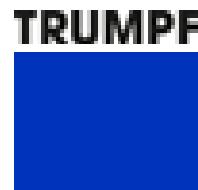
## Avantages:

- High power
- High beam quality
- Very efficient cooling and longitudinal thermal gradient only.

# Thin Disk Laser



four laser head combined give 8kW optical power at 1030 nm (IR)

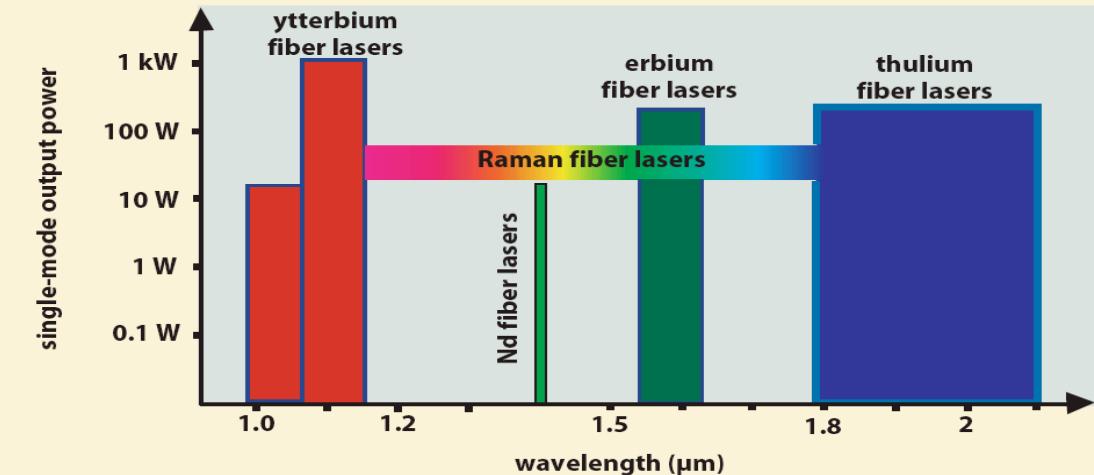


# Fiber Lasers

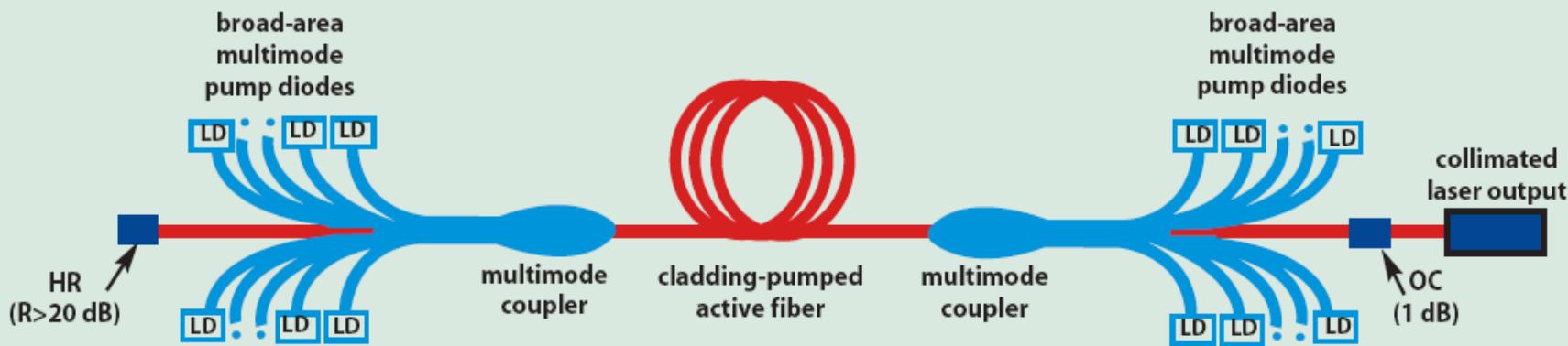
Single mode

Multimode

(Courtesy of IPG Photonics Corp. Bill Shiner)

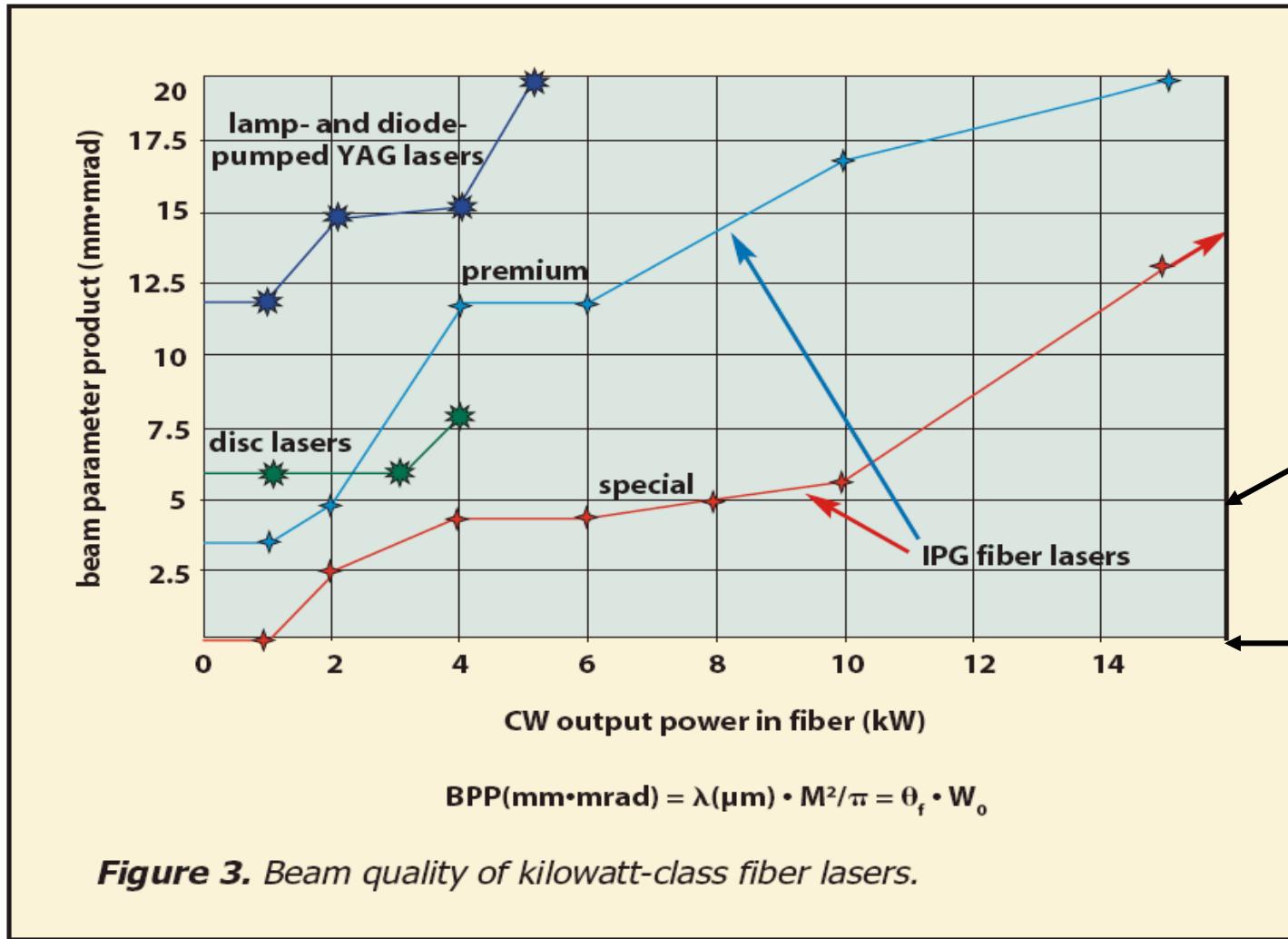


**Figure 2.** Wavelengths available with single-mode fiber lasers.



**Figure 1.** Schematic of a typical single-mode fiber laser utilizing single-emitter diodes.

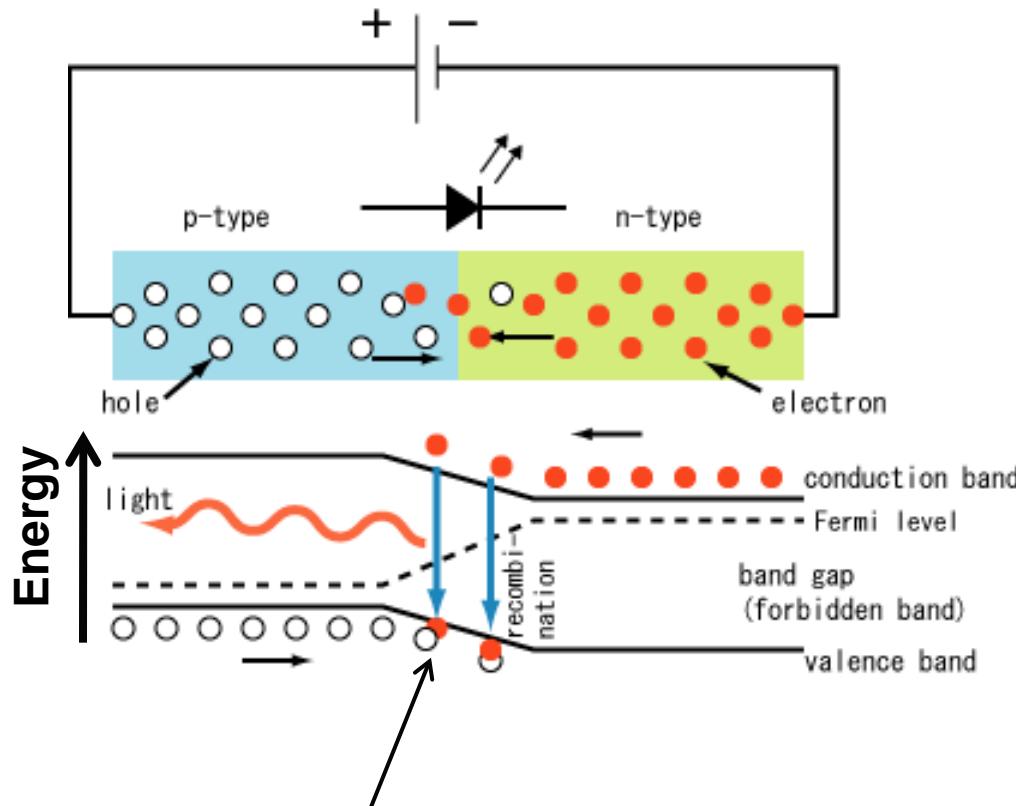
# Fiber Lasers



**Figure 3.** Beam quality of kilowatt-class fiber lasers.

(Courtesy of IPG Photonics Corp)

# Light Emitting Diodes



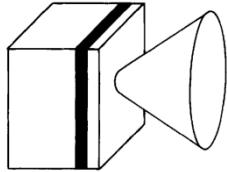
Recombination of electrons and holes in the p-n junction liberates energy, emitted as light.

Differences between LED and LD (laser diode):

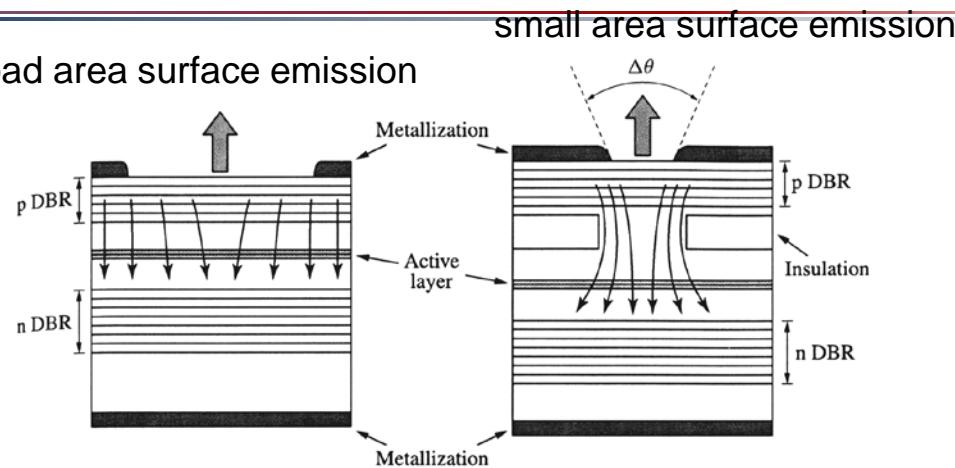
- LED devices do **not** reach light amplification condition
- LD have designed resonator (feedback) to promote **stimulated emission**
- LED are **spontaneous emission** devices
- LD emission is more directed

# Light Emitting Diodes

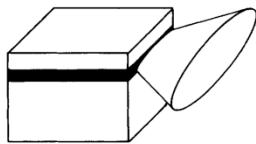
## Surface emitting LEDs



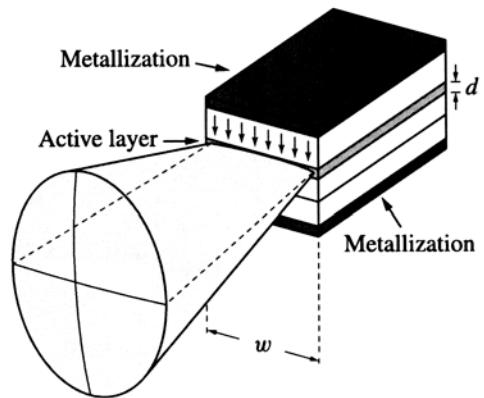
Broad area surface emission



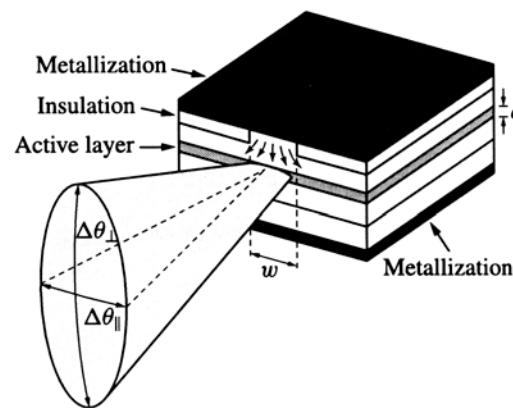
## Edge emitting LEDs



Broad area edge emission



Strip geometry edge emission



Emitting surface of the LED can be quite small:

dia.  $\sim 10 \mu\text{m}$  – for surface emission

1  $\mu\text{m} \times 10 \mu\text{m}$  – for edge emitting LED

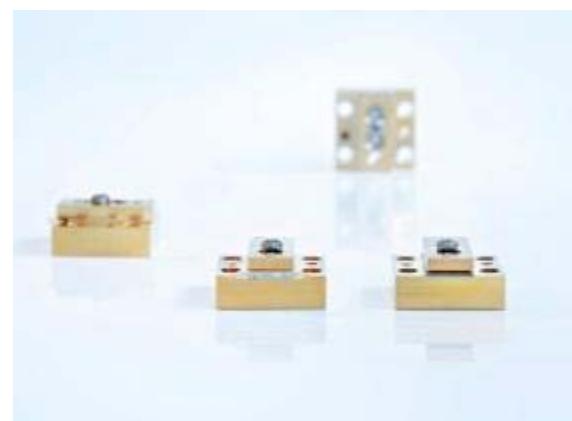
# Laser Diodes: Production Chain



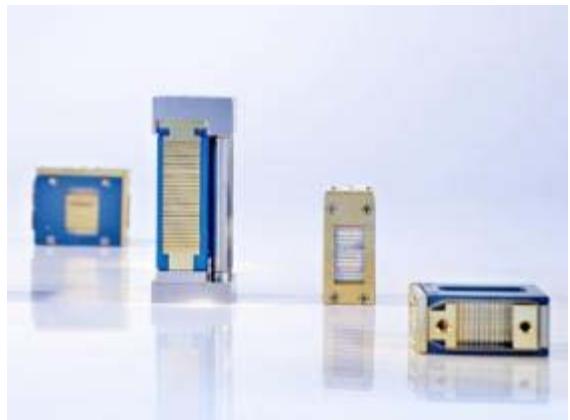
Epitaxialy grown  
semiconductor thin films



Individual emitters or emmitter  
bars by lithography process



single emmiters mounted on  
passive cooler



vertical stack (high power) of  
laser diode bars



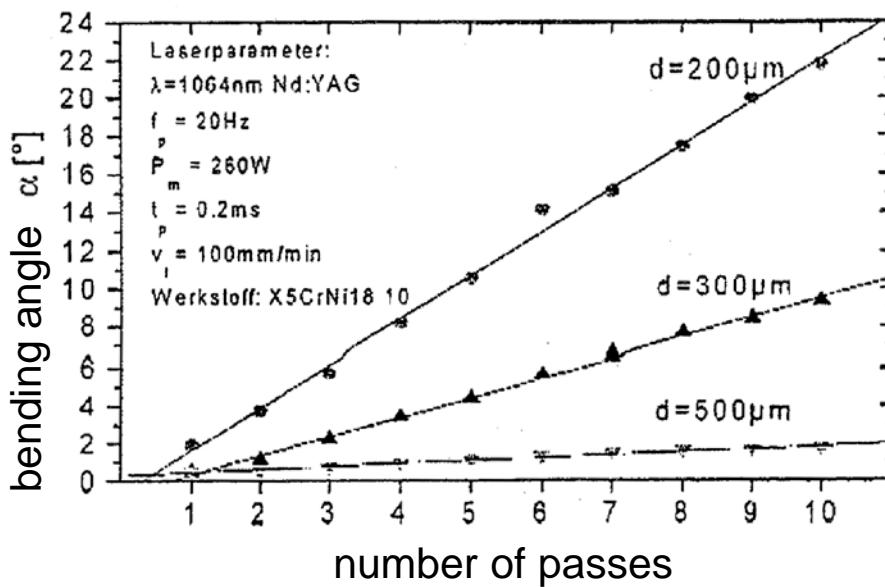
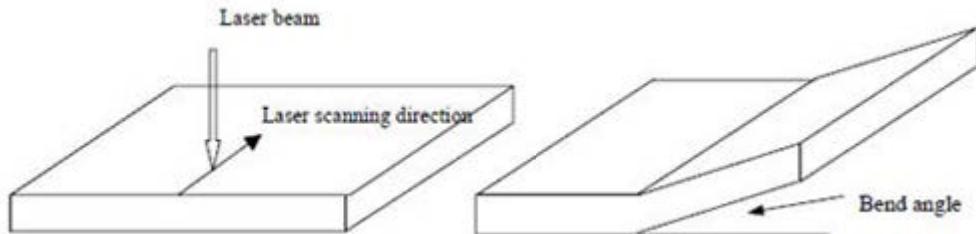
fibre coupled and water cooled laser diode  
modules



<http://www.jenoptik.com/en-diode-laser>

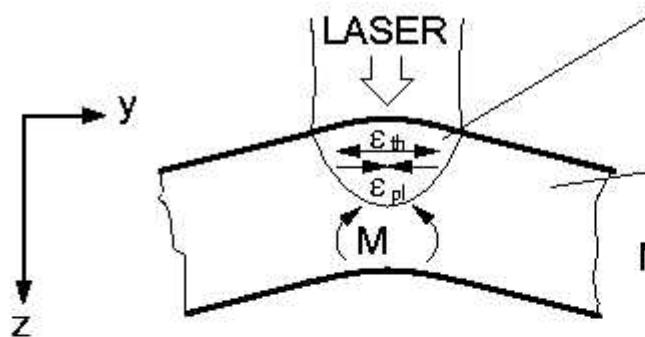


# Laser Bending



# Laser Bending

## heating - counterbending



heated zone

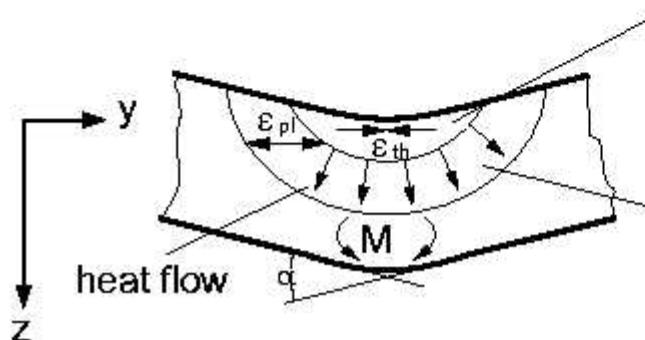
compressive stress

1

sheet metal

M: Moment due to section  
modulus and bend angle  $\alpha$

## cooling - positive bending



compressed zone  
tensile stress

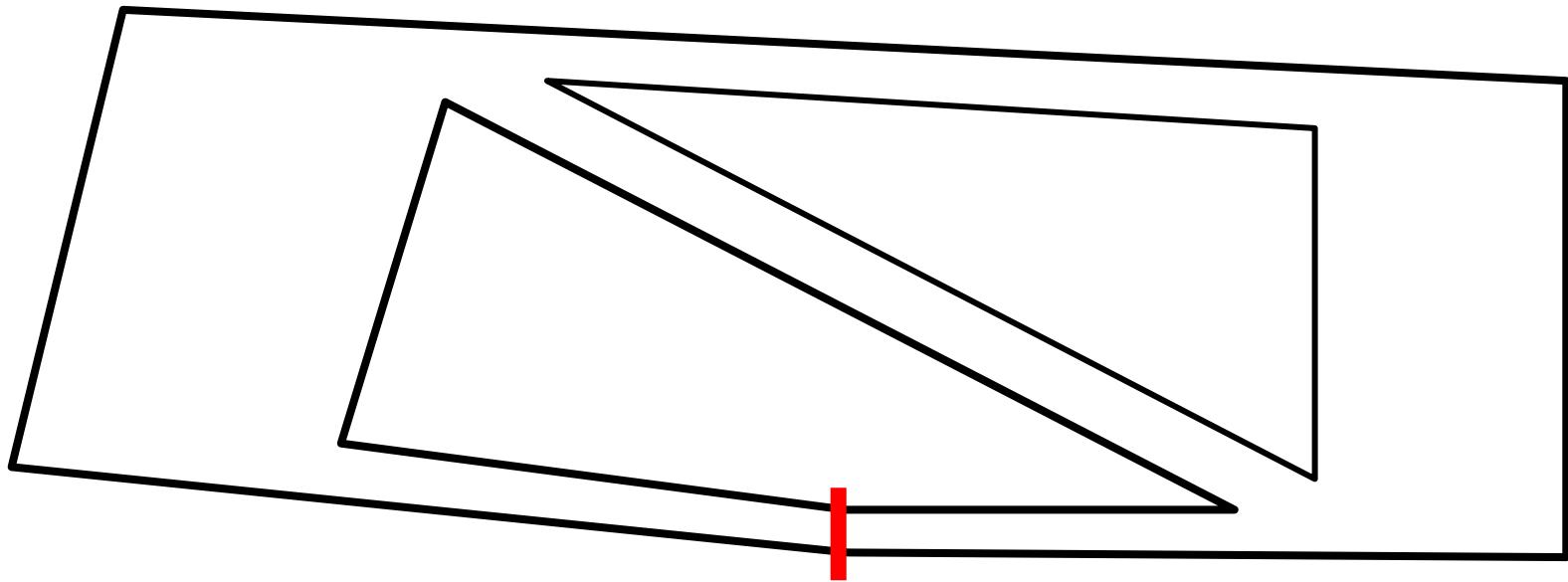
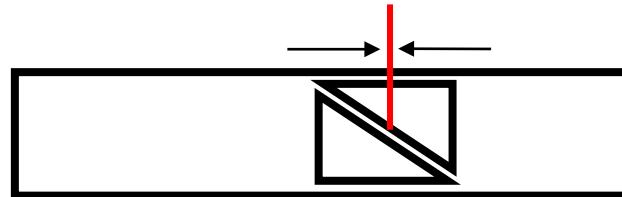
2

expansion  
compressive stress

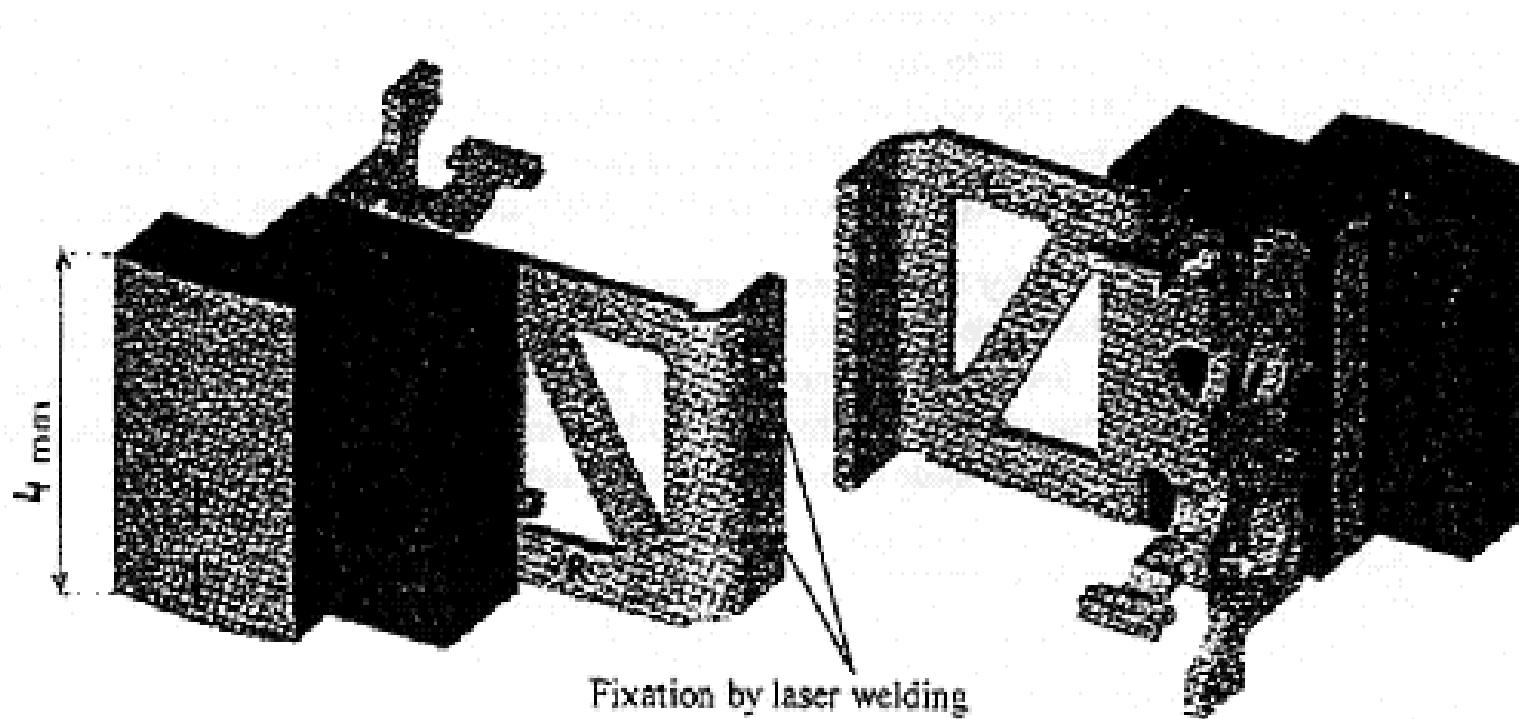
3

# Laser Bending

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# Laser Welding



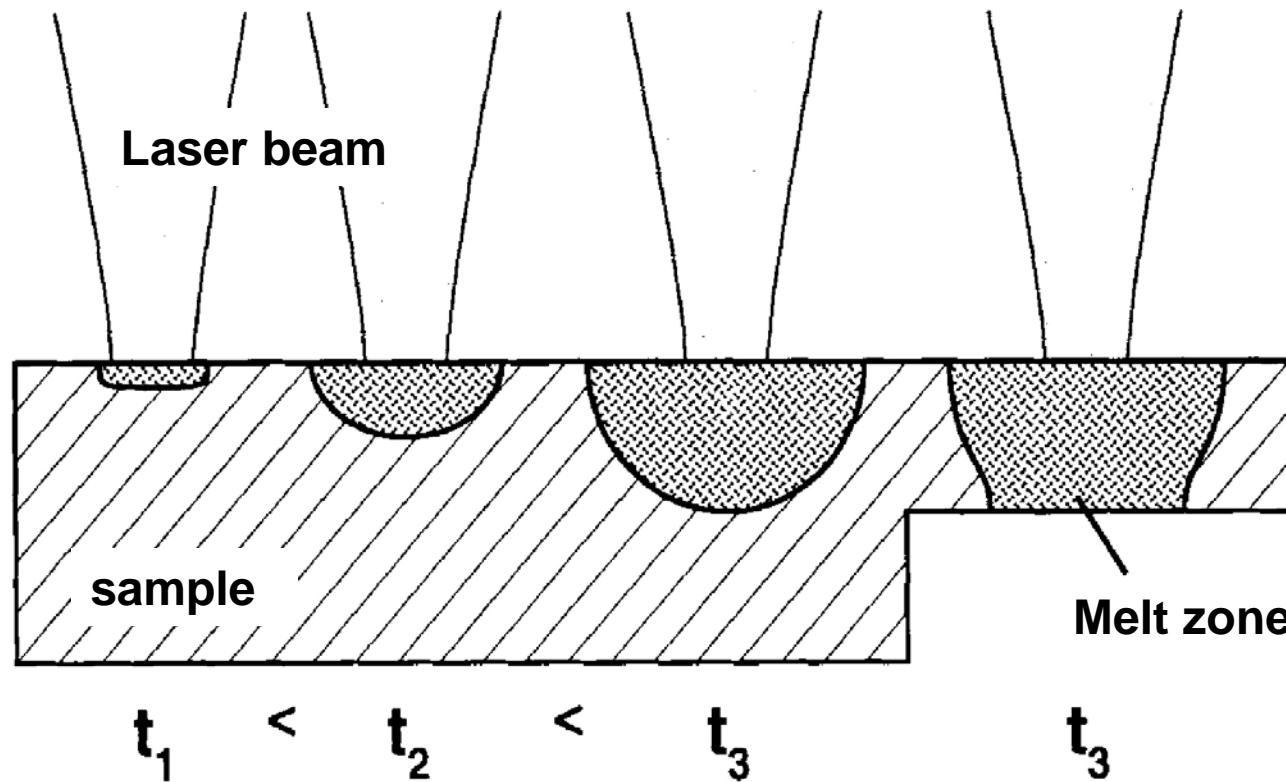
*The audio chip for the DCC (Digital Compact Cassette) mounted onto a special carrier for laser-adjustment. After 'rough' fixation by laser welding, the carrier allows an accurate adjustment of two important degrees of freedom of the chip: the track-height and the azimuth of the thin film heads. If the parts L, R and M are irradiated by short intense laser pulses, their lengths change by the thermo-mechanical shrinkage: the parts become shorter by a few microns. The carrier fulfils the function of an actuator for fine-adjustment of the audio chip. The carrier also acts as a support for mounting the audio chip into the DCC-player: 'the actuator is part of the product'. It can be mass-produced by simple stamping from thin metal sheet.*

# Laser Welding

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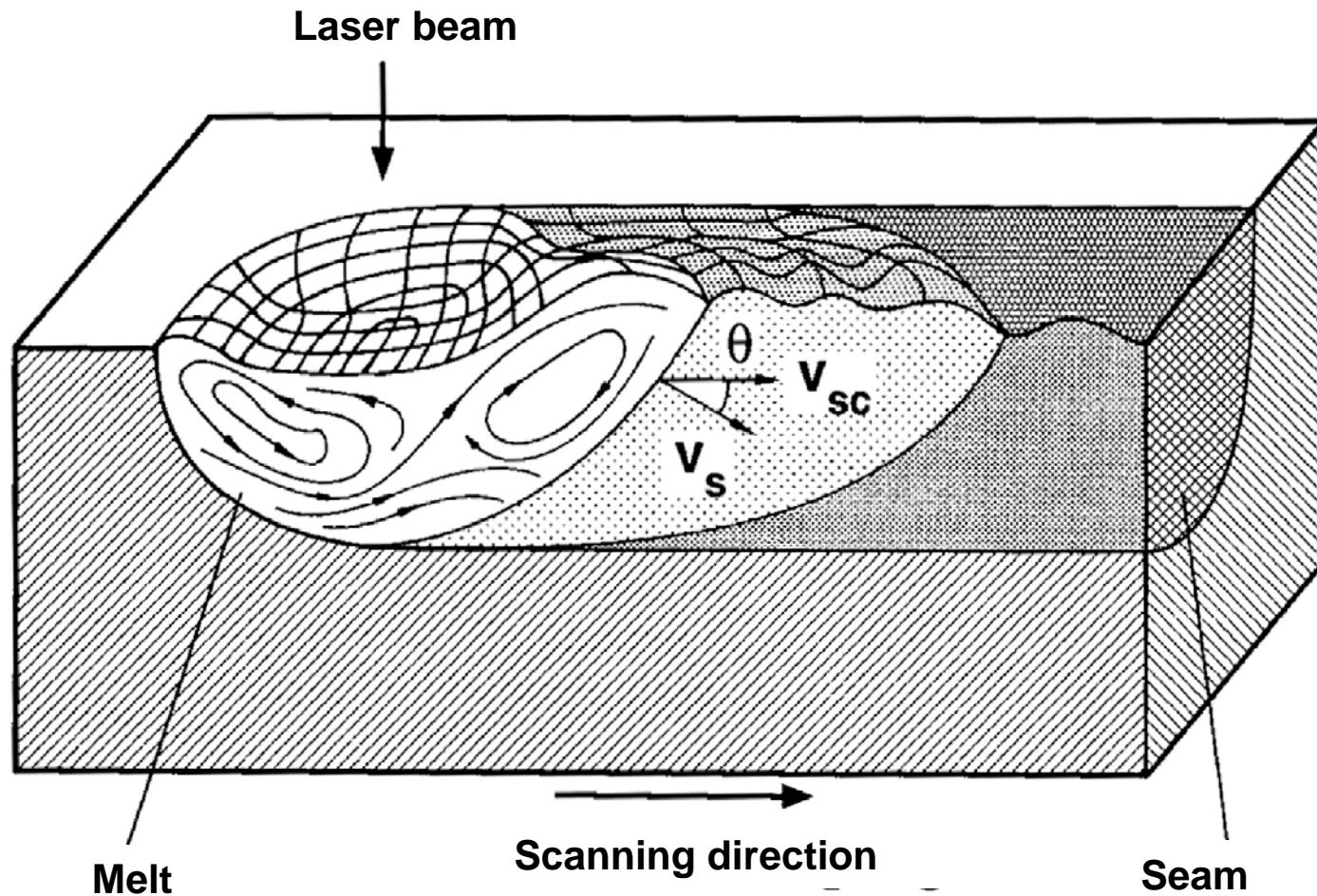
- conduction welding
- deep welding

# Laser Welding



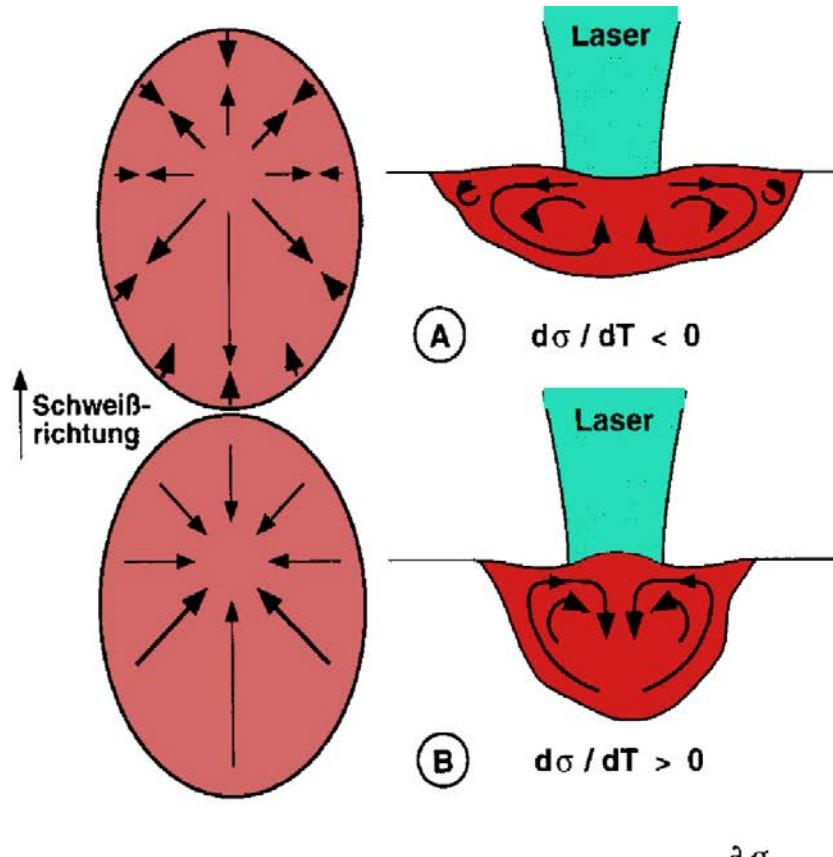
Principle of conduction welding

# Laser Welding – Melt Dynamics



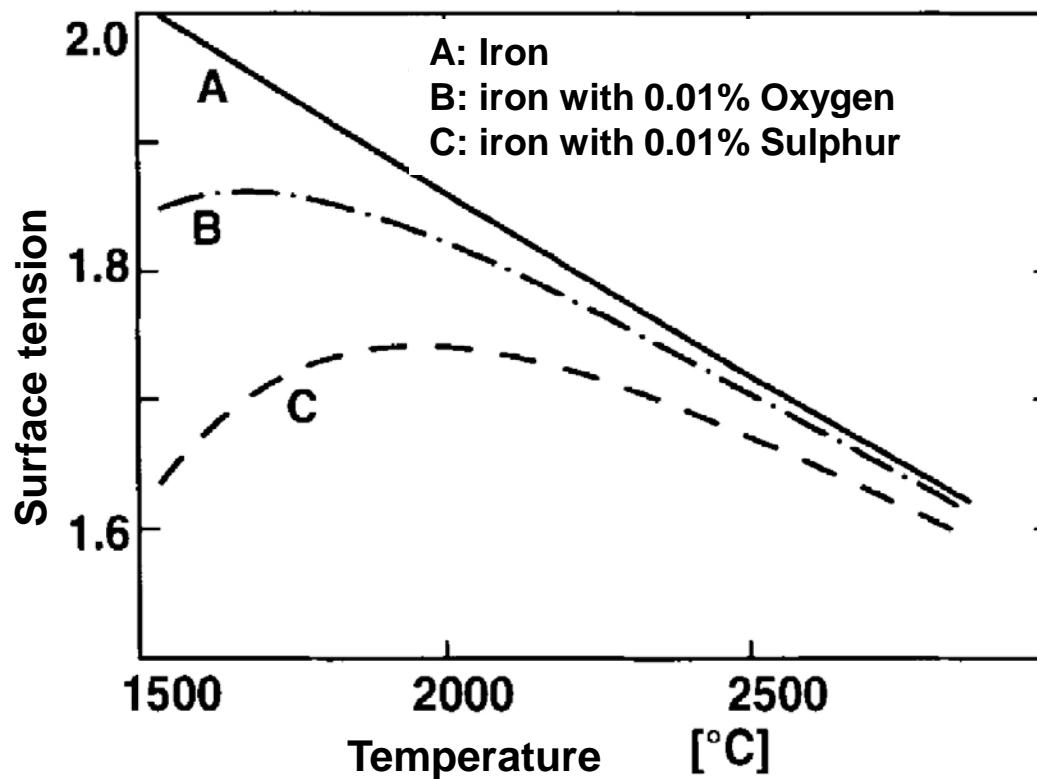
Melt bath dynamics and deformed surface

# Laser Welding – Marangoni Effect



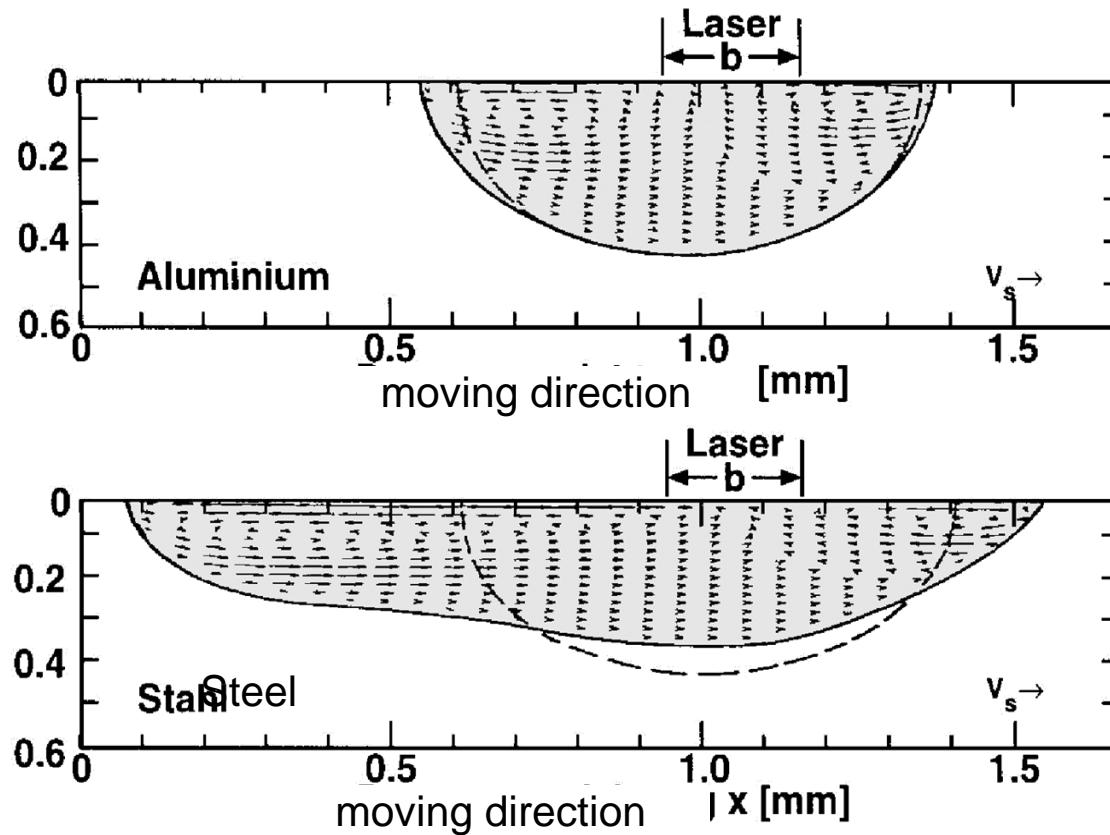
Melt zone for different surface tension on temperature dependencies

# Laser Welding



Melt zone for different surface tension on temperature dependencies

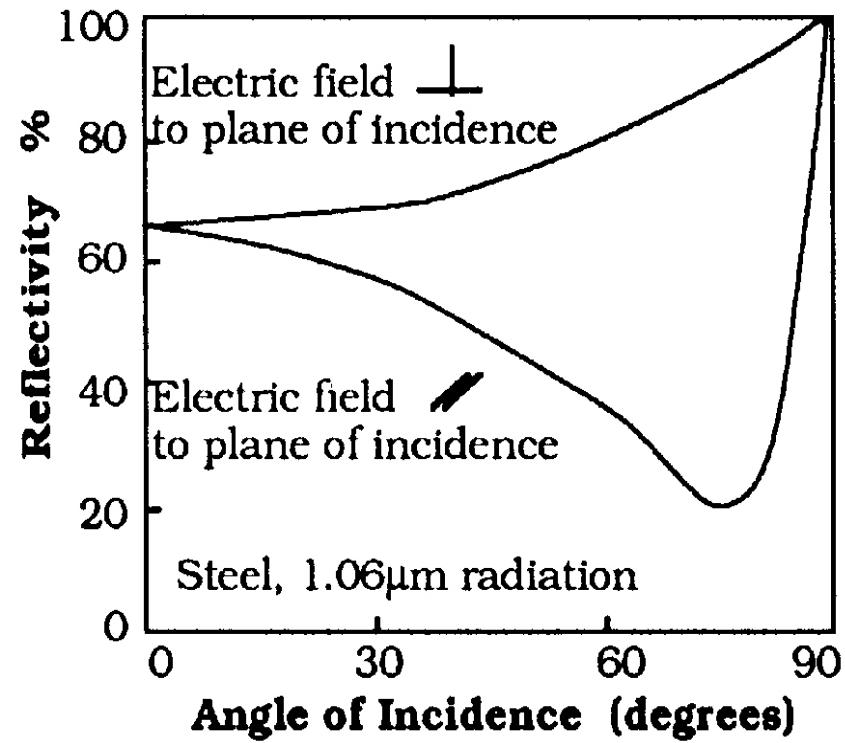
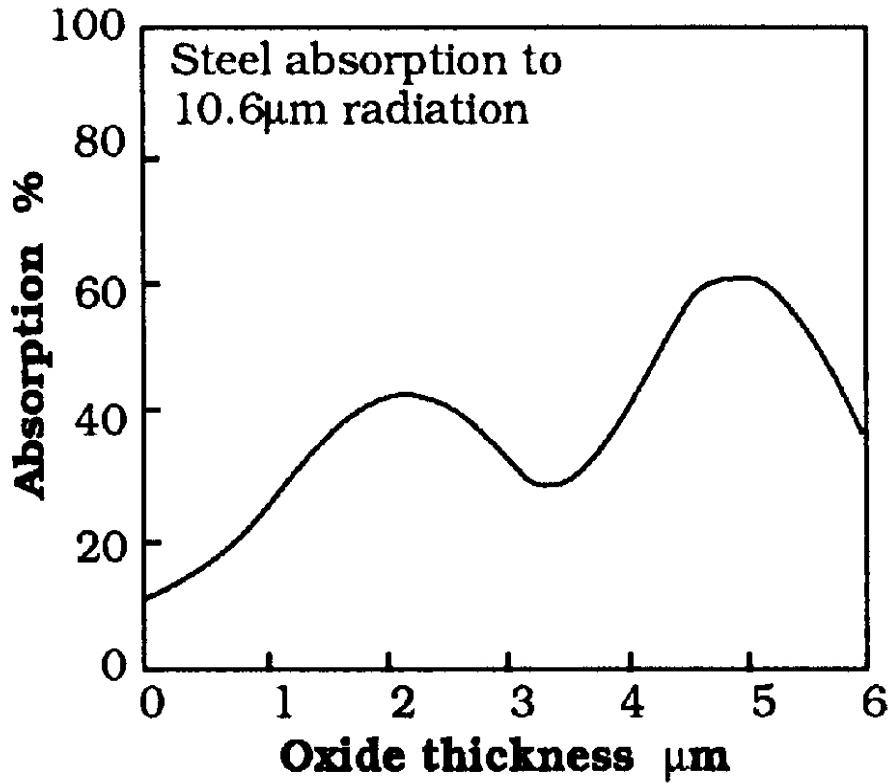
# Laser Welding



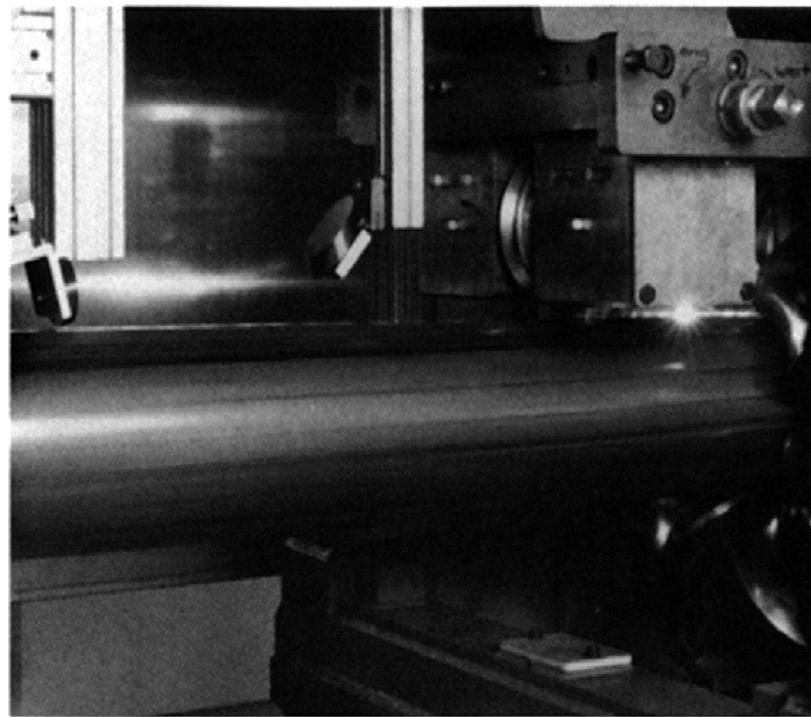
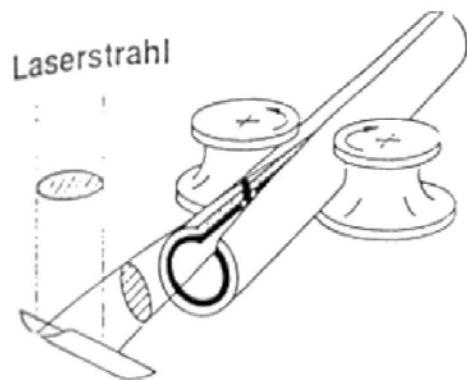
Numerically simulated melt isotherm for steel and aluminium  
at 6 mm/s scanning speed

(the dashed line marks the melt zone if convention is not taken into account)

# Laser soldering



# Laser Welding



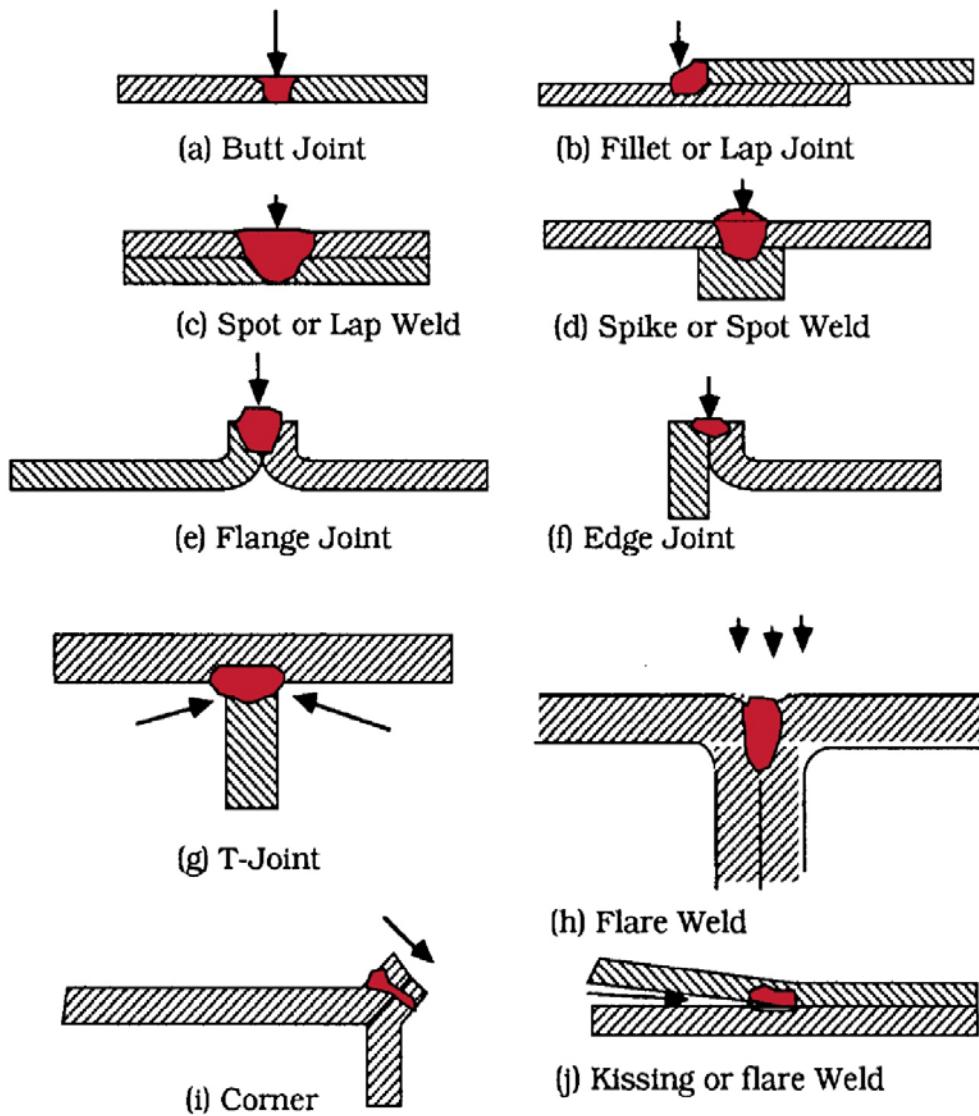
$$P_L = 20 \text{ kW}$$

$$6 \text{ mm} < s < 12 \text{ mm}$$

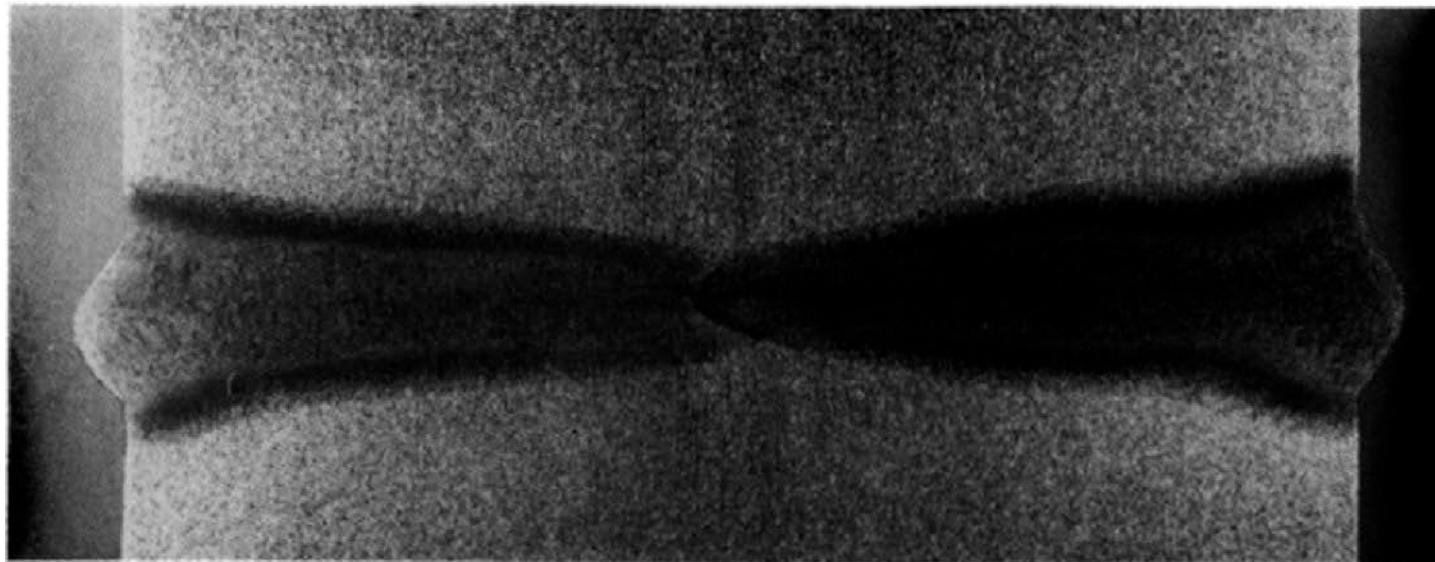
$$20 \text{ m/min} > v_s > 5 \text{ m/min}$$

Polarisation welding of tubes  
polarisation is chosen to increase the reflectivity on the walls  
to guide the light deeper

# Laser Welding



# Laser Welding



50 mm

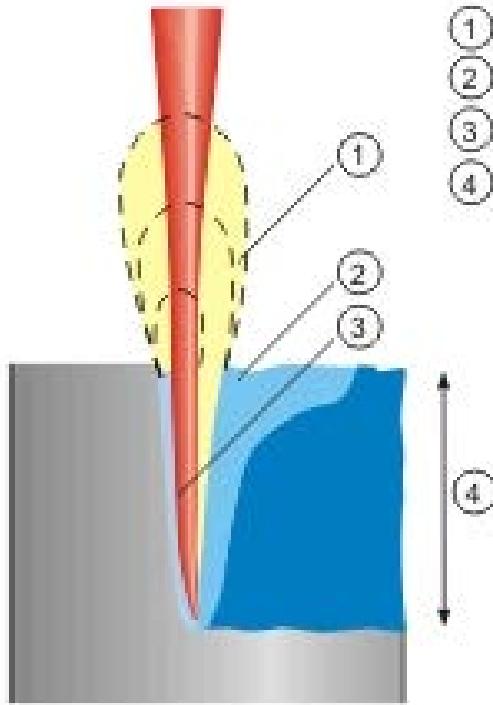
$V_{s1} = 0.6 \text{ m/min}$	$F = 10$	$P_L = 20 \text{ kW}$
$V_{s2} = 0.6 \text{ m/min}$	$r_F = 330 \mu\text{m}$	

**Double side welded seam of 50mm thick steel**

# Deep Laser Welding

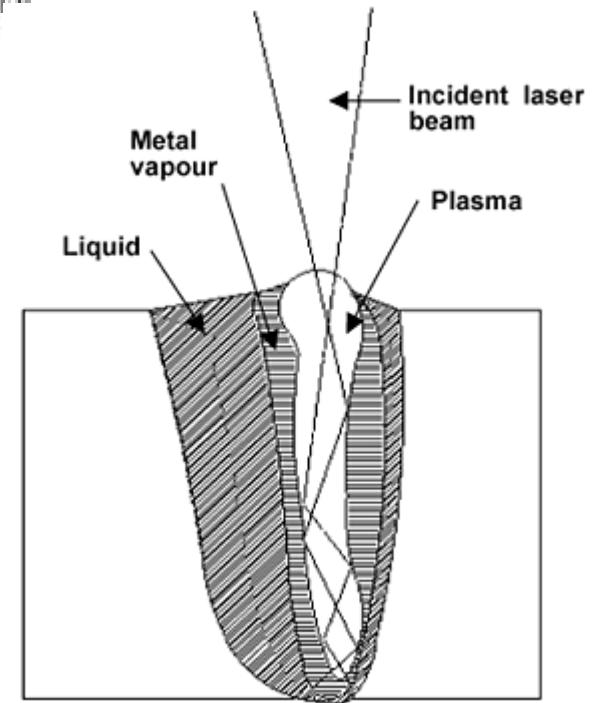


Heat conduction welding



Deep penetration welding

- ① Plasma cloud
- ② Molten material
- ③ Keyhole
- ④ Weld depth



# Laser Welding

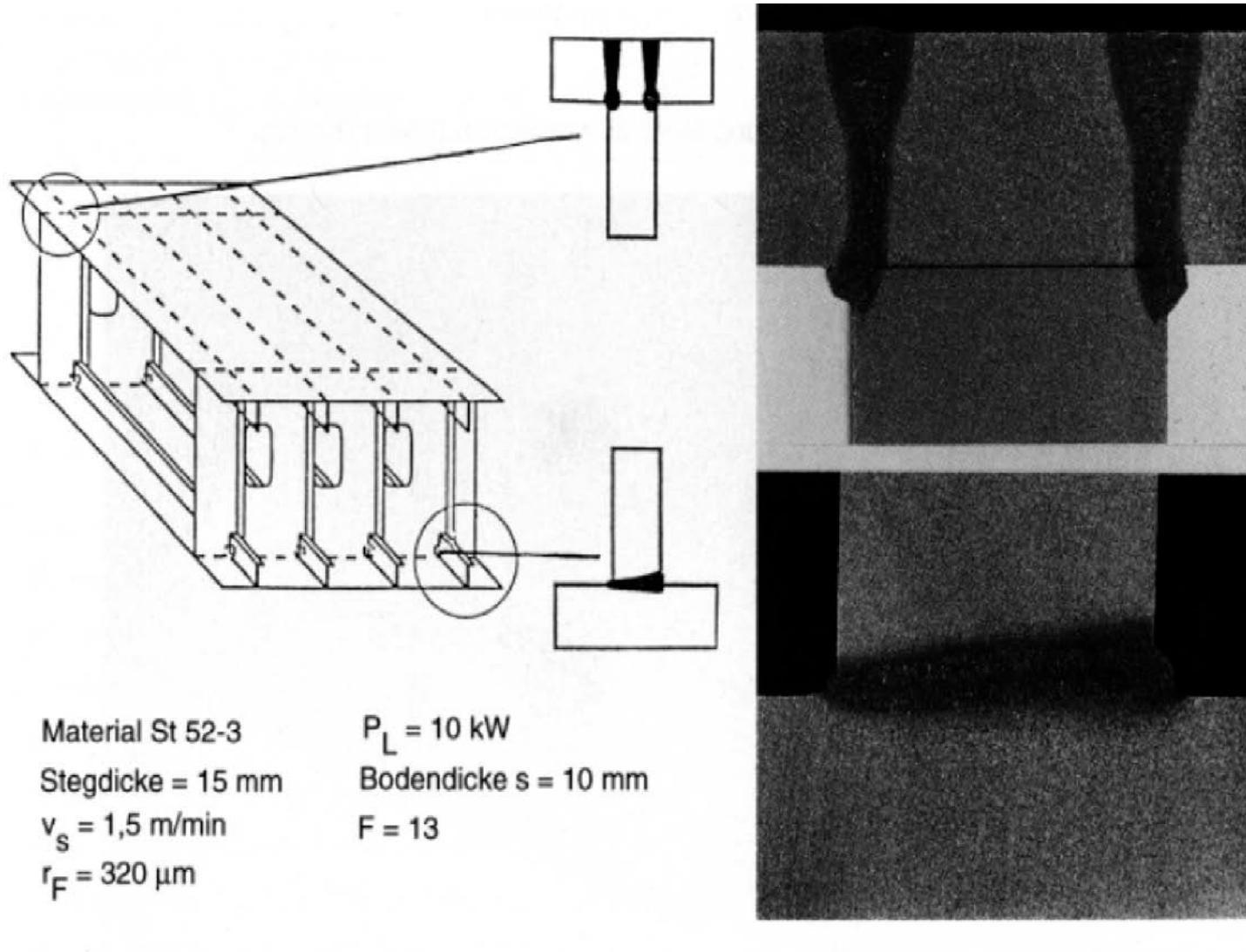
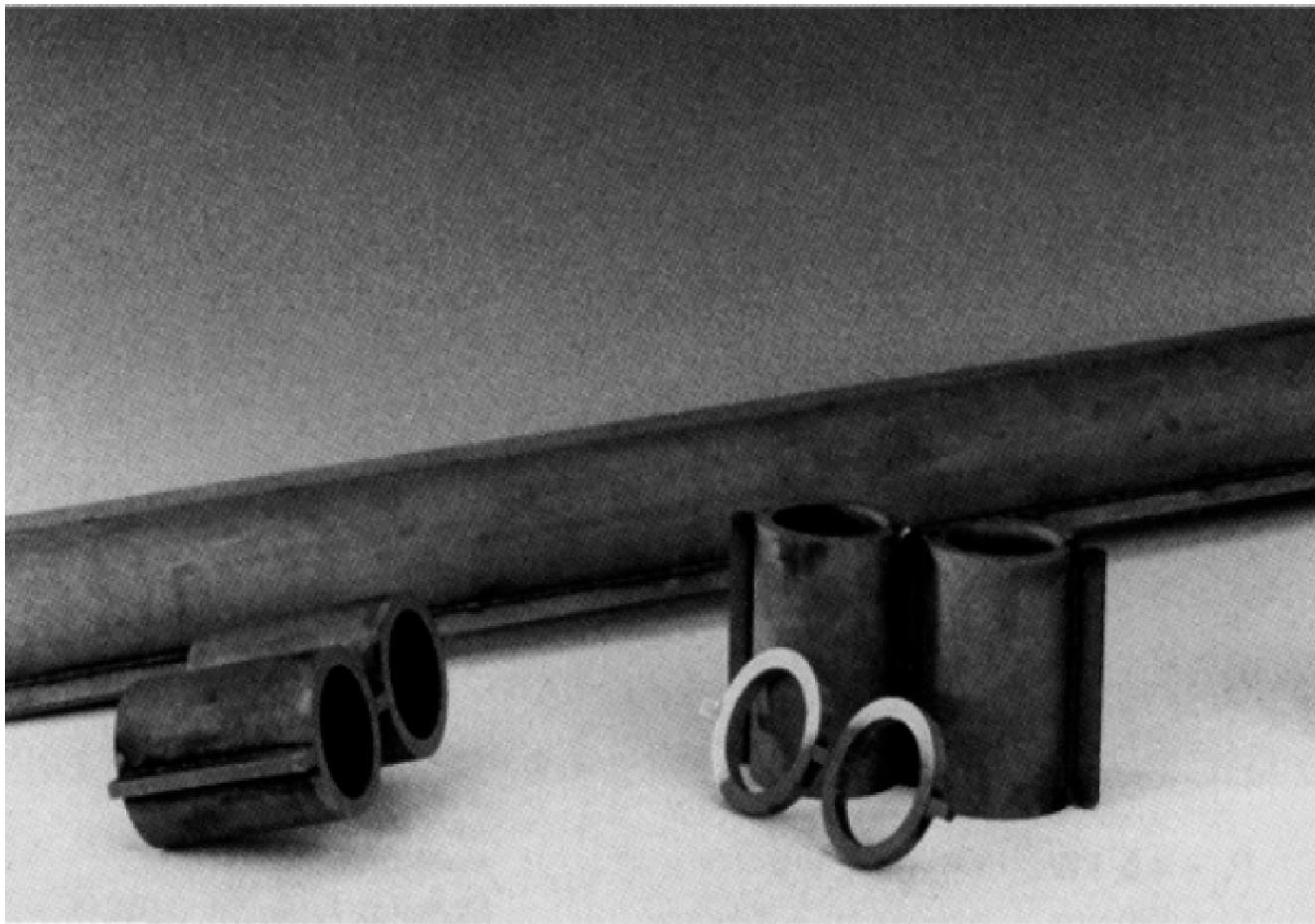


Abb. 2.3.4      Laserstrahlschweißungen an Doppelböden

# Laser Welding



$$P_L = 10 \text{ kW}$$

$$r_F = 320 \mu\text{m}$$

$$F = 13,5$$

$$v_s = 2,7 \text{ m/min}$$

$$s = 6 \text{ mm}$$

# Laser Welding

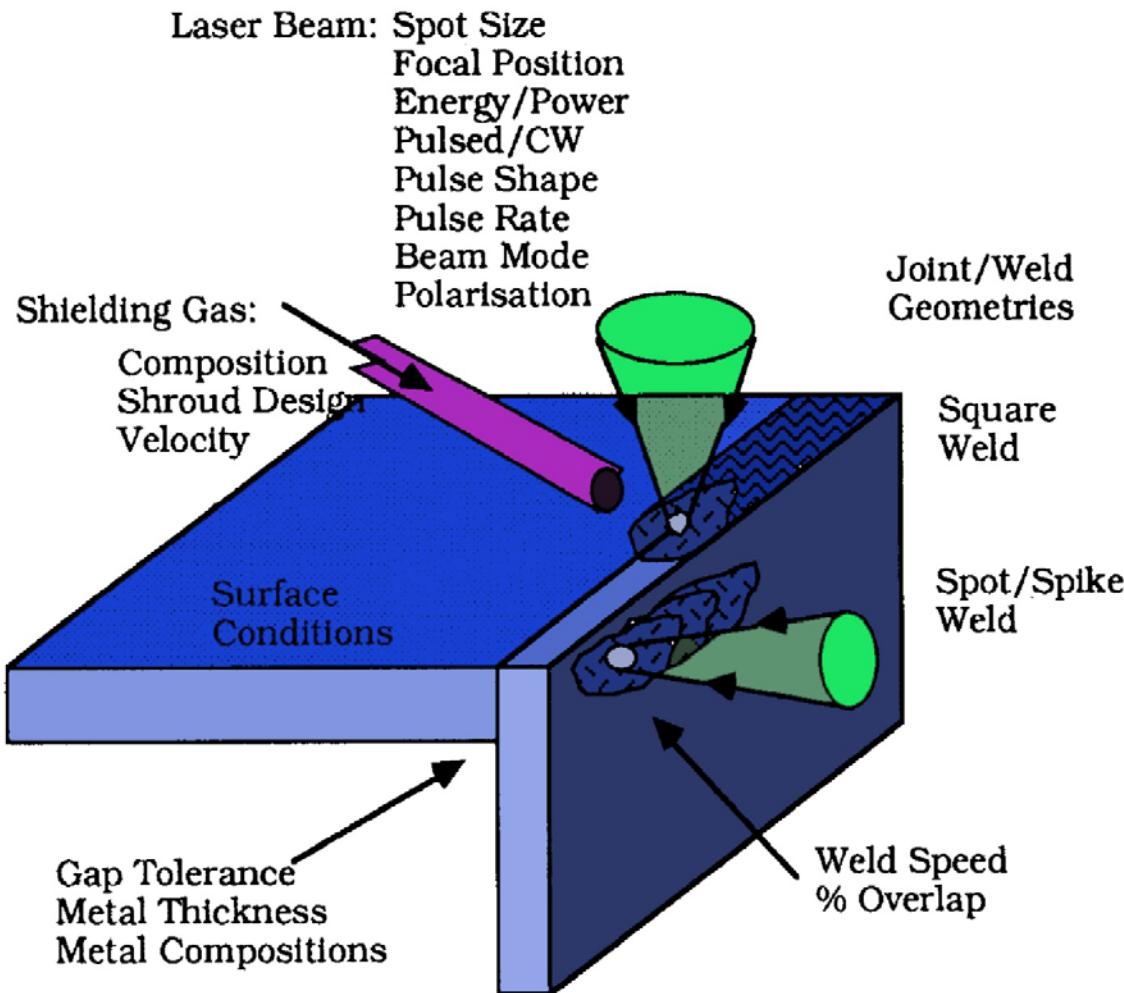
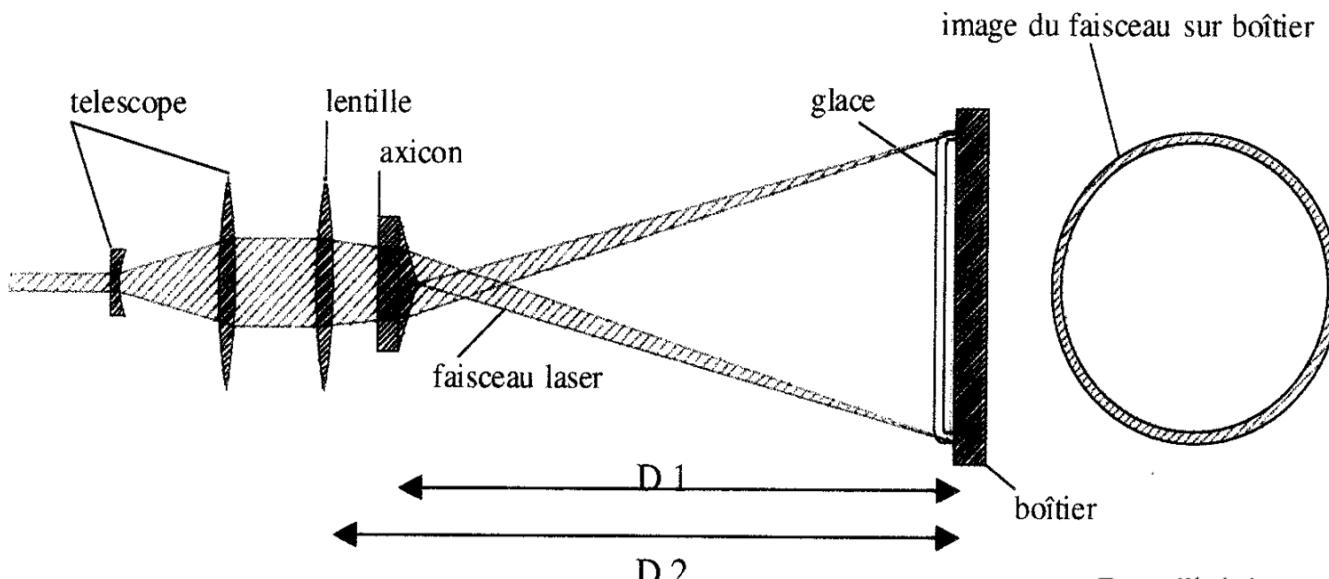
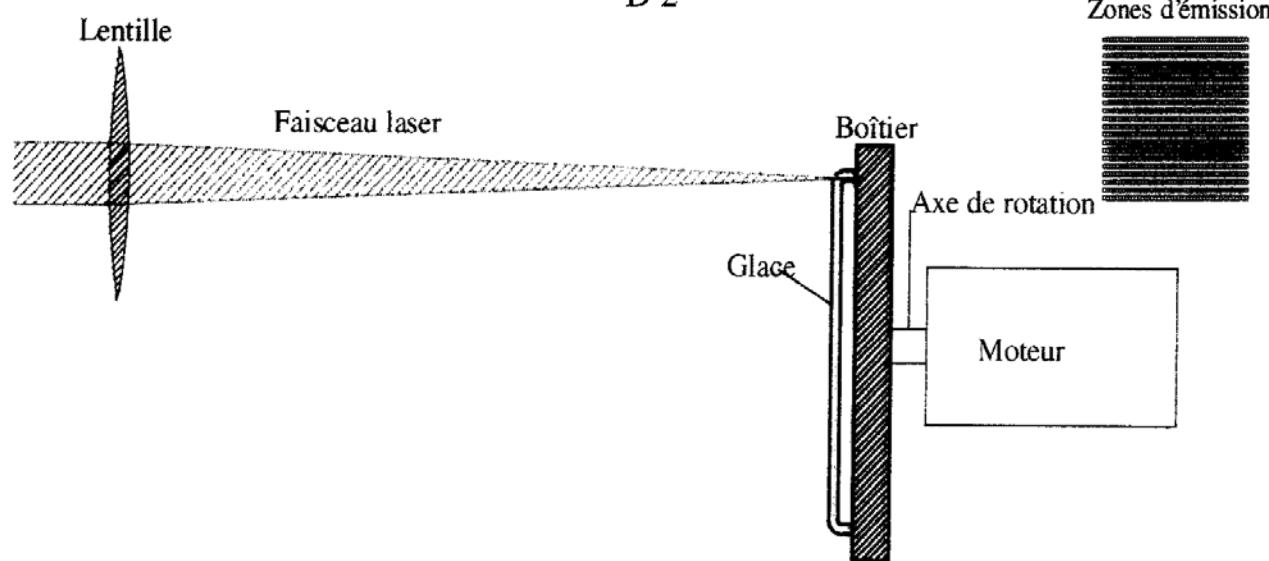


Fig. 4.10. The main process parameters.

# Laser Welding of Plastic



Ring soldering  
using axicon



Ring soldering using  
rotation of the object